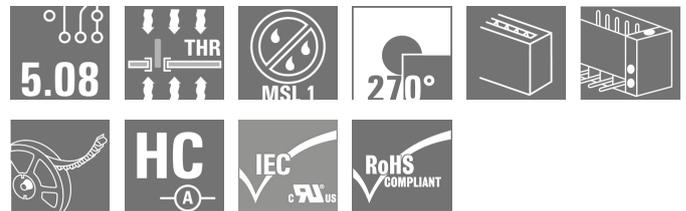


**SL-SMT 5.08HC/05/270FH 1.5SN BK RL**

**Weidmüller Interface GmbH & Co. KG**  
 Klingenbergstraße 26  
 D-32758 Detmold  
 Germany

www.weidmueller.com

**Product image**


High-temperature-resistant, straight, open pin header.  
 Packed in box or tape. On tape and with 1.5 mm solder pin, optimised for automatic assembly. 3.2 mm solder pin suitable for reflow and wave soldering. The pin headers provide space for labelling and can be coded. HC = High Current.

**General ordering data**

Version	PCB plug-in connector, male header, Solder flange, THT/THR solder connection, 5.08 mm, Number of poles: 5, 270°, Solder pin length (l): 1.5 mm, tinned, black, Tape
Order No.	<a href="#">1876950000</a>
Type	SL-SMT 5.08HC/05/270FH 1.5SN BK RL
GTIN (EAN)	4032248467402
Qty.	335 pc(s).
Product data	IEC: 400 V / 27.5 A UL: 300 V / 18.5 A
Packaging	Tape

Creation date March 26, 2021 2:01:14 AM CET

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**Technical data**
**Dimensions and weights**

Depth	12 mm	Depth (inches)	0.472 inch
Height	12.5 mm	Height (inches)	0.492 inch
Height of lowest version	11 mm	Net weight	3.332 g
Width	35.2 mm	Width (inches)	1.386 inch

**System specifications**

Product family	OMNIMATE Signal - series BL/SL 5.08	Type of connection	Board connection
Mounting onto the PCB	THT/THR solder connection	Pitch in mm (P)	5.08 mm
Pitch in inches (P)	0.2 inch	Outgoing elbow	270°
Number of poles	5	Number of solder pins per pole	1
Solder pin length (l)	1.5 mm	Solder pin length tolerance	0 / -0.3 mm
Solder pin dimensions	d = 1.2 mm, Octagonal	Solder eyelet hole diameter (D)	1.4 mm
Solder eyelet hole diameter tolerance (D)+	0,1 mm	L1 in mm	20.32 mm
L1 in inches	0.8 inch	Number of rows	1
Pin series quantity	1	Volume resistance	≤5 mΩ
Can be coded	Yes	Plugging force/pole, max.	9 N
Pulling force/pole, max.	7 N		

**Material data**

Insulating material	LCP GF	Colour	black
Colour chart (similar)	RAL 9011	Insulating material group	IIIa
Comparative Tracking Index (CTI)	≥ 175	Moisture Level (MSL)	1
UL 94 flammability rating	V-0	Contact material	CuMg
Contact surface	tinned	Layer structure of solder connection	1...3 μm Ni / 2...4 μm Sn matt
Layer structure of plug contact	1...3 μm Ni / 2...4 μm Sn matt	Storage temperature, min.	-40 °C
Storage temperature, max.	70 °C	Operating temperature, min.	-50 °C
Operating temperature, max.	100 °C	Temperature range, installation, min.	-30 °C
Temperature range, installation, max.	100 °C		

**Rated data acc. to IEC**

tested acc. to standard	IEC 60664-1, IEC 61984	Rated current, min. number of poles (Tu=20°C)	27.5 A
Rated current, max. number of poles (Tu=20°C)	19 A	Rated current, min. number of poles (Tu=40°C)	24 A
Rated current, max. number of poles (Tu=40°C)	16.5 A	Rated voltage for surge voltage class / pollution degree II/2	400 V
Rated voltage for surge voltage class / pollution degree III/2	320 V	Rated voltage for surge voltage class / pollution degree III/3	250 V
Rated impulse voltage for surge voltage class/ pollution degree II/2	4 kV	Rated impulse voltage for surge voltage class/ pollution degree III/2	4 kV
Rated impulse voltage for surge voltage class/ contamination degree III/3	4 kV		

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**Technical data****Rated data acc. to CSA**

Institute (CSA)



Certificate No. (CSA)

200039-1176845

Rated voltage (Use group B / CSA) 300 V

Rated voltage (Use group D / CSA) 300 V

Rated current (Use group B / CSA) 18.5 A

Rated current (Use group D / CSA) 18.5 A

Reference to approval values

Specifications are maximum values, details - see approval certificate.

**Rated data acc. to UL 1059**

Institute (UR)



Certificate No. (UR)

E60693

Rated voltage (Use group B / UL 1059) 300 V

Rated voltage (Use group D / UL 1059) 300 V

Rated current (Use group B / UL 1059) 18.5 A

Rated current (Use group D / UL 1059) 10 A

Reference to approval values

Specifications are maximum values, details - see approval certificate.

**Packing**

Packaging	Tape	VPE length	0 m
VPE width	0 m	VPE height	0 m
Tape depth (T2)	15.5 mm	Tape width (W)	56 mm
Tape pocket depth (K0)	15 mm	Tape pocket height (A0)	12.3 mm
Tape pocket width (B0)	35 mm	Tape pocket separation (P1)	16 mm
Tape hole separation (E)	1.75 mm	Tape pocket separation (F)	26.2 mm
Tape reel diameter $\varnothing$ (A)	330 mm	Surface resistance	$R_s = 10^9 - 10^{12} \Omega$

**Classifications**

ETIM 6.0	EC002637	ETIM 7.0	EC002637
ECLASS 9.0	27-44-04-02	ECLASS 9.1	27-44-04-02
ECLASS 10.0	27-44-04-02	ECLASS 11.0	27-46-02-01

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**Technical data**
**Important note**

IPC conformity	Conformity: The products are developed, manufactured and delivered according international recognized standards and norms and comply with the assured properties in the data sheet resp. fulfill decorative properties in accordance with IPC-A-610 "Class 2". Further claims on the products can be evaluated on request.
Notes	<ul style="list-style-type: none"> <li>• Gold-plated contact surfaces on request</li> <li>• Rated current related to rated cross-section &amp; min. No. of poles.</li> <li>• Diameter of solder eyelet <math>D = 1.4 + 0.1 \text{ mm}</math></li> <li>• Solder eyelet diameter <math>D = 1.5 + 0.1 \text{ mm}</math>, from 9 poles</li> <li>• P on drawing = pitch</li> <li>• Rated data refer only to the component itself. Clearance and creepage distances to other components are to be designed in accordance with the relevant application standards.</li> <li>• Long term storage of the product with average temperature of <math>50 \text{ }^\circ\text{C}</math> and average humidity 70%, 36 months</li> </ul>

**Approvals**

Approvals



ROHS	Conform
UL File Number Search	E60693

**Downloads**

Approval/Certificate/Document of Conformity	<a href="#">Declaration of the Manufacturer</a>
Engineering Data	<a href="#">STEP</a>

**Data sheet**

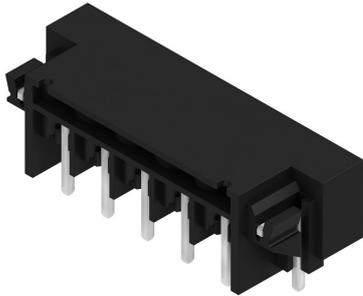
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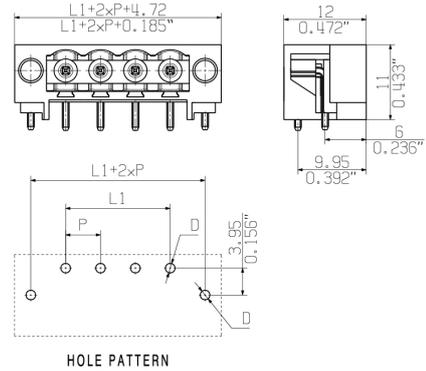
www.weidmueller.com

**Drawings**

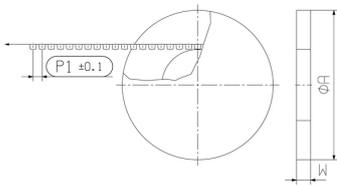
**Product image**



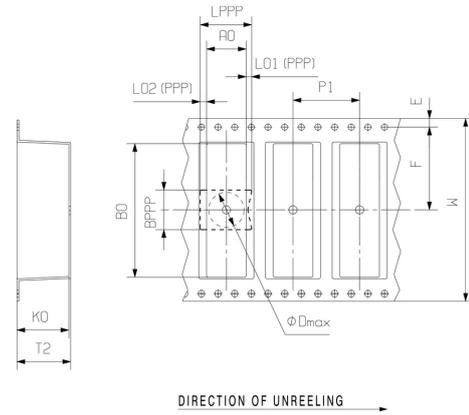
**Dimensional drawing**



**Dimensional drawing**



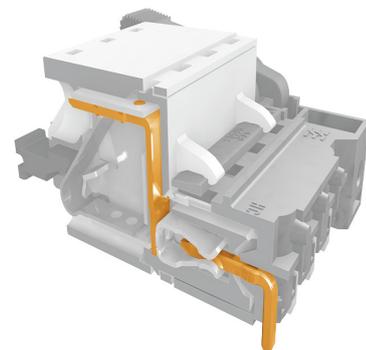
**Dimensional drawing**



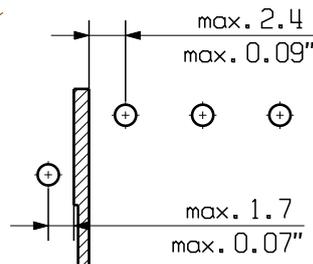
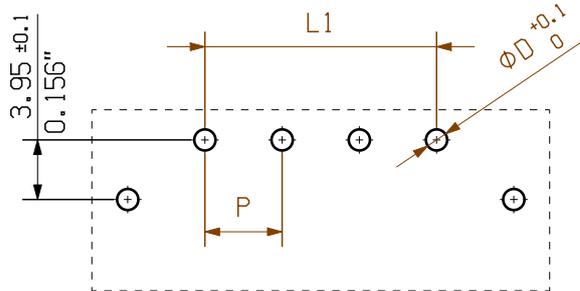
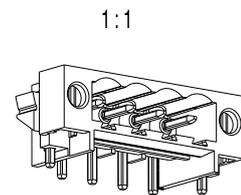
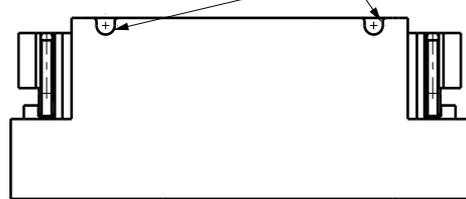
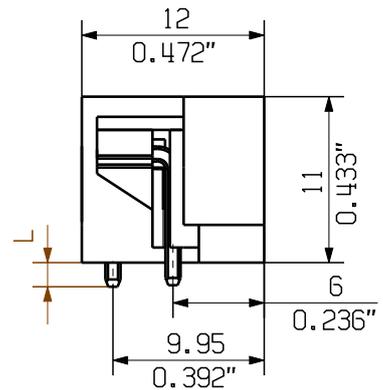
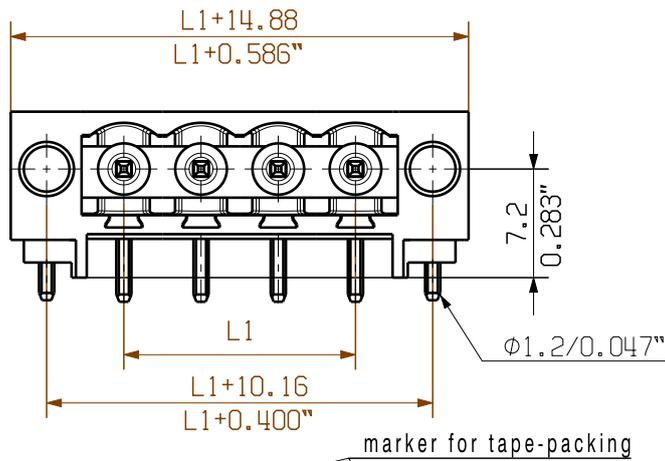
**Example of use**



**Product benefits**



Safe power transmission  
 Proven properties



hole pattern

paste free area

For the mounting of PCBs, it should be noted that the rated data given in the catalogue relates only to the connection elements. The necessary creepage and clearance paths must be observed in connection with the respective applicant in accordance to VDE 0110. The current-carrying capacity and pitch tolerance is to be determined according to DIN IEC 326 part 3 very fine.

Weidmüller connectors are tested to the DIN VDE 0627 standard, and are valid for its field of application. Provided that the connectors are used to the intended purpose, all requirements with respect to the occurring of electrical, mechanical, thermic and corrosive stress will be satisfied.

D=1.4/0.055" (reflow soldering)  
recommendation for automatic assembly  
(1.4mm for n=2...8)

P=Pitch

shown: SL-SMT 5.08HC/04/270FH

1,5	0 -0.3
3,2	0.1 -0.3
pin lenght L	tolerance

8	35,56	1,400	±0.1
7	30,48	1,200	
6	25,40	1,000	
5	20,32	0,800	
4	15,24	0,600	
3	10,16	0,400	
2	5,08	0,200	
n	L1 [mm]	L1 [Inch]	

GENERAL TOLERANCE:  
DIN ISO 2768-m



91033/4  
03.02.17 HERTEL\_S 00

Modification

**Weidmüller**

Cat.no.:  
**3 37899 17**

Drawing no. Issue no.  
Sheet 04 of 06 sheets



Date Name

Drawn 23.03.2004 DOMRATH\_M

Responsible HERTEL\_S

Checked 06.02.2017 HELIS\_MA

Approved LANG\_T

**SL-SMT 5.08HC/.../270...**  
STIFTLISTE  
MALE HEADER

Scale: 2/1

Supersedes: .

Product file: SL-SMT 5.08

7313

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## Recommended wave soldering profiles

**Weidmüller Interface GmbH & Co. KG**  
 Klängenbergstraße 16  
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 Germany  
 Fon: +49 5231 14-0  
 Fax: +49 5231 14-292083  
 www.weidmueller.com

### Single Wave:



### Double Wave:



### Wave soldering profiles

Wired connection elements should be processed in accordance with the DIN EN 61760-1 standard. We have included two recommendations for practical wave soldering profiles, with which Weidmüller PCB terminals and connectors are qualified.

When choosing a suitable profile for your application, the following factors also need to be considered:

- PCB thickness
- Proportion of Cu in the layers
- Single/double-sided assembly
- Product range
- Heating and cooling rates

The single and double wave profiles each indicate the recommended operating range, including the maximum soldering temperature of 260°C. In practice, the maximum soldering temperature is quite often well below the above maximum profile.

## Recommended reflow soldering profile

**Weidmüller Interface GmbH & Co. KG**  
 Klingenbergstraße 16  
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 Germany  
 Fon: +49 5231 14-0  
 Fax: +49 5231 14-292083  
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### Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:

- Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- Maximum heating rate
- Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically  $\leq +3\text{K/s}$ . In parallel the solder paste is ‚activated‘. The time above melting point of  $217^\circ\text{C}$  the paste gets liquid and components and boards begin to connect. The maximum temperature of  $245^\circ\text{C}$  to  $254^\circ\text{C}$  should stay between 10 and 40 seconds. In the cooling phase at  $\geq -6\text{K/s}$  solder is cured. Board and components cool down while avoiding cold cracks.